



Progress in Nondestructive Testing and Evaluation (NDT&E)

Guest Editors:

Dr. Shiwei Liu

College of Engineering,
Huazhong Agricultural University,
Wuhan 430070, China

Dr. Bo Feng

School of Mechanical Science
and Engineering, Huazhong
University of Science and
Technology, Wuhan 430074,
China

Deadline for manuscript
submissions:

closed (20 June 2025)

Message from the Guest Editors

Dear Colleagues,

The non-destructive testing and evaluation (NDT&E) technique has been driven by advanced sensors, signal processing methods, material, artificial intelligence, smart sensing and various applications, which is also playing an important role in applied sciences. However, the challenges brought by the deep explorations for theoretical and physical mechanisms of the NDT&E method and sophisticated applications make the NDT&E develop faster than that in any of the recent decades. Therefore, this Special Issue is intended for the presentation of new ideas, experimental results and the latest progress in the field of NDT&E from theory to its practical use.

This Special Issue invites authors to submit their high-quality research articles that cover different topics of NDT&E progress. Subjects that will be discussed in this Special Issue focus not only on the newest methods, technologies and applications, but also on the progressive results of their future work.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, Embase, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Contact Us

Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](https://twitter.com/AtApplsci)